

Typical Applications Circuit



Pin Descriptions

Pin Number		Number		
Pin Name	SOT223 TO252	U-DFN2030-8 SO-8EP	Function	
GND	2	1	Ground	
IN	1	2, 3, 4	Voltage Input Pin	
OUT	3	5, 6, 7	Voltage Output Pin	
ADJ	NA	8	Output feedback pin for adjustable version only—a resistor divider from this pin to the OUT pin and ground sets the output voltage.	
NC	NA	8	No connection for fixed output version.	
EP/TAB	_	_	The exposed pad (EP) removes heat from the package, and it is recommended that the EP is connected to a copper area. The die is electrically connected to the exposed pad. It is recommended to connect the EP externally to GND, but it should not be the only ground connection.	

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Ratings	Unit
ESD HBM	Human Body Model ESD Protection	2000	V
ESD MM	Machine Model ESD Protection	200	V
V _{IN}	Input Voltage	-0.3 to +6.0	V
Vout	OUT Voltage	-0.3 to V _{IN} +0.3	V
lout	Continuous Load Current	Internal Limited	—
T _{ST}	Storage Temperature Range	-65 to +150	°C
TJ	Maximum Junction Temperature	150	°C

Recommended Operating Conditions (@ T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Мах	Unit
V _{IN}	Input Voltage	2.2	5.5	V
I _{OUT}	Output Current	0	1.5	A
T _A	Operating Ambient Temperature	-40	+85	°C
TJ	Operating Junction Temperature (Note 5)	-40	+125	°C

4. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated are not implied. Exposure to absolute-maximum rated Notes: conditions for extended periods may affect device reliability. 5. Operating junction temperature must be evaluated and derated as needed, based on ambient temperature (T_A), power dissipation (P_D), maximum

allowable operating junction temperature (T_{J-MAX}), and package thermal resistance (θ_{JA}).



Electrical Characteristics (@ $T_A = +25^{\circ}C$, $V_{IN} = 3.3V$, $I_{OUT} = 10mA$, $C_{IN} = 10\mu$ F, $C_{OUT} = 10\mu$ F, unless otherwise specified.)

Minimum and maximum limits are guaranteed through test, design, or statistical correlation. Typical values represent the most likely parametric norm at $T_A = +25^{\circ}$ C, and are provided for reference purposes only.

Symbol	Parameter	Test Condition	ons	Min	Тур	Max	Unit
		$V_{IN} = V_{IN-MIN}$ to V_{IN-MAX} ,	T _A = +25°C	0.584	0.605	0.626	N/
VADJ	ADJ Pin Voltage	$I_{OUT} = 10$ mA to 1.5A	Over temp	0.575	_	0.635	v
	AD L Dia Dias Current		T _A = +25°C		50		nA
IADJ	ADJ PIN Blas Current	$V_{IN} = V_{IN-MIN}$ to V_{IN-MAX}	Over temp	_	_	750	
\/	Dropout Voltage (Note 6)		T _A = +25°C	—	190	240	m)/
VDROPOUT	Diopout voltage (Note 6)	$I_{OUT} = 1.5A, V_{OUT} = 2.5V$	Over temp	—	—	280	mv
	Line Regulation (Note 7)	View View to View	T _A = +25°C	_	0.04	_	0/ //
ΔVOUT/ΔVIN	Line Regulation (Note 7)	VIN = VIN-MIN to VIN-MAX	Over temp	—	0.05		%)/V
	Load Regulation (Note 7)	$1 \dots 10 \text{ m}$ $1 \dots 1 \dots 1$	T _A = +25°C	—	0.18	_	0/ /A
Δνουτ/Διουτ	Load Regulation (Note 7)	$I_{OUT} = 10$ mA to 1.5A	Over temp	—	0.33		-70/A
	Ground Pin Current in Normal	$1 \qquad 10m \wedge to 15 \wedge$	T _A = +25°C	—	1.0	1.2	mA
IGND	Operation Mode	$I_{OUT} = 10$ mA to 1.5A	Over temp	—	—	1.3	
I _{OUT-PK}	Peak Output Current	$V_{OUT} \ge V_{OUT - NOM} -5\%$			—	_	А
	Short Circuit Current	OUT Grounded	T _A = +25°C	—	3.7		A
ISC			Over temp	2	_		
t _{d(off)}	Turn-Off Delay	From $V_{EN} < V_{IL}$ to $V_{OUT} = OF$	F, I _{OUT} = 1.5A	—	25		μs
t _{d(on)}	Turn-On Delay	From $V_{EN} > V_{IH}$ to $V_{OUT} = ON$, $I_{OUT} = 1.5A$		—	25		μs
2022		V _{IN} = 3.0V, I _{OUT} = 1.5A, f = 120Hz		—	65	_	16
PSRR	Ripple Rejection	V _{IN} = 3.0V, I _{OUT} = 1.5A, f = 1kHz		_	61		dВ
On(I/f)	Output Noise Density	$F = 120$ Hz, $C_{OUT} = 10$ µF Ceramic		_	1.0	_	µV/√Hz
,		BW = 100Hz – 100kHz,		_	400	_	
e _n	Output Noise Voltage	$C_{OUT} = 10 \mu F$ Ceramic			100		μV(rms)
T _{SHDN}	Thermal Shutdown Threshold	T _J Rising		—	170		
T _{HYS}	Thermal Shutdown Hysteresis	TJ Falling From TSHDN	TJ Falling From TSHDN		10	_	°C
		U-DFN2030-8 (Note 8) SO-8EP (Note 8)		_	85.0		
0	Thermal Resistance Junction-to-			_	52.8	_	°C/W
θ _{JA}	Ambient	SOT223 (Note 8)		_	105.7		
		TO252 (Note 8)		—	87.8		
		U-DFN2030-8 (Note 8)		—	17.0		
Alla	Thermal Resistance Junction-to-Case	SO-8EP (Note 8)		—	10.0	_	°C/W
OlC		SOT223 (Note 8)		_	18.5	_	
		TO252 (Note 8)	_	17.3	_		

Notes: 6. Dropout voltage is the minimum voltage difference between the input and the output at which the output voltage drops 2% below its nominal value.

For any output voltage less than 2.5V, the minimum V_{IN} operating voltage is the limiting factor.

7. The line and load regulation specification contains only the typical number. However, the limits for line and load regulation are included in the adjust voltage tolerance specification.

8. Device mounted on 2" x 2" FR-4 substrate PCB, 2oz copper with minimum recommended pad layout.



Typical Performance Characteristics (@ T_J = +25°C, V_{IN} = 2.7V, C_{IN} = 10µF, C_{OUT} = 10µF, I_{OUT} = 10mA, V_{OUT} = 1.8V)







Typical Performance Characteristics (continued)

(@ $T_J = +25^{\circ}C$, $V_{IN} = 2.7V$, $C_{IN} = 10\mu$ F, $C_{OUT} = 10\mu$ F, $I_{OUT} = 10$ mA, $V_{OUT} = 1.8V$)





Application Note

Input Capacitor

A minimum 2.2µF ceramic capacitor is recommended between IN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance can be increased without limit. A larger input capacitor, like 10µF, provides better load transient response. This input capacitor must be located as close as possible to the device to assure input stability and to reduce noise. For PCB layout, a wide copper trace is required for both IN and GND pins. A lower ESR capacitor type allows the use of less capacitance, while a higher ESR type requires more capacitance.

Output Capacitor

The output capacitor is required to stabilize and help the transient response of the LDO. The AP7363 is stable with any type of capacitor with no limitations on minimum or maximum ESR. The device is designed to have excellent transient response for most applications with a small amount of output capacitance. The device is also stable with multiple capacitors in parallel, which can be of any type of value. Additional capacitance helps reduce undershoot and overshoot during transient loads. This capacitor must be placed as close as possible to OUT and GND pins for optimum performance.

Adjustable Operation

The AP7363 provides output voltage from 0.6V to 5.0V through external resistor divider as shown below.



The output voltage is calculated by the following equation:

$$V_{OUT} = V_{REF} \left(1 + \frac{R_1}{R_2} \right)$$

Where $V_{REF} = 0.6V$ (the internal reference voltage)

Rearranging the previous equation gives the following equation that is used for adjusting the output to a particular voltage:

$$R_1 = R_2 \left(\frac{V_{OUT}}{V_{REF}} - 1 \right)$$

To maintain the stability of the internal reference voltage, R_2 must be kept smaller than $10k\Omega$.

No Load Stability

Other than external resistor divider, no minimum load is required to keep the device stable. The device will remain stable and regulated in no load condition.



Application Note (continued)

Stability and Phase Margin

Any regulator that operates using a feedback loop must be compensated in such a way as to ensure adequate phase margin, which is defined as the difference between the phase shift and -180 degrees at the frequency where the loop gain crosses unity (0 dB). For most LDO regulators, the ESR of the output capacitor is required to create a zero to add enough phase lead to ensure stable operation. The AP7363 has an internal compensation circuit that maintains phase margin regardless of the ESR of the output capacitor—any type of capacitors can be used.

The following charts show the gain/phase plot of the AP7363 with an output of 1.2V, 10µF ceramic output capacitor, and delivering 1.5A load current and no load. The phase margin is about 90°, which is very stable.



Short-Circuit Protection

When the output current at the OUT pin is higher than the current limit threshold, the current limit protection triggers and clamps the output current to prevent overcurrent and to protect the regulator from damage due to overheating.

Thermal Shutdown Protection

Thermal protection disables the output when the junction temperature rises to approximately +170°C, which allows the device to cool down. When the junction temperature reduces to approximately +160°C, the output circuitry is enabled again. Depending on power dissipation, thermal resistance, and ambient temperature, the thermal protection circuit may cycle on and off. This cycling limits the heat dissipation of the regulator and protects it from damage due to overheating.

Low Quiescent Current

The AP7363, consuming only around 0.5mA for all input range, provides great power saving in portable and low-power applications.

Output Noise

This is the integrated value of the output noise over a specified frequency range. Input voltage and output load current are kept constant during the measurement. Results are expressed in μ Vrms or μ V \sqrt{Hz} .

The AP7363 is a low-noise regulator and requires no external noise reduction capacitor. Output voltage noise is typically 100µVrms, and overall noise level is between 100 Hz and 100 kHz.

Noise is specified in two ways:

Output noise density is the RMS sum of all noise sources, measured at the regulator output, at a specific frequency (measured with a 1Hz bandwidth). This type of noise is usually plotted on a curve as a function of frequency.

Output noise voltage is the RMS sum of spot noise over a specified bandwidth. Spot noise is measured in units $\mu V/\sqrt{Hz}$ or nV/\sqrt{Hz} , and total output noise is measured in μV (rms). The primary source of noise in low-dropout regulators is the internal reference.



Application Note (continued)

Power Dissipation

The device power dissipation and proper sizing of the thermal plane connected to the thermal pad is critical to avoid thermal shutdown and ensure reliable operation. Power dissipation of the device depends on input voltage and load conditions and can be calculated by:

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT}$$

The maximum power dissipation, handled by the device, depends on the junction-to-ambient thermal resistance and maximum ambient temperature, which can be calculated by the following equation:

$$P_{D_max} = \frac{(+150^{\circ}C - T_A)}{R_{\theta}JA}$$

Ordering Information



	Part Number	Baakaga Cada	Packaging	7"/13" Tape and Reel		
	Fait Nulliber	Fackage Code	(Note 9)	Quantity	Part Number Suffix	
Pb-	AP7363-XXHA-7	HA	U-DFN2030-8	3000/Tape & Reel	-7	
Pb-	AP7363-XXSP-13	SP	SO-8EP	2500/Tape & Reel	-13	
Pb.	AP7363-XXE-13	E	SOT223-3L	2500/Tape & Reel	-13	
Pb-	AP7363-XXD-13	D	TO252-3L	2500/Tape & Reel	-13	

Note: 9. TO252 and SOT223 are only available with fixed output version.



Marking Information

(1) U-DFN2030-8

(Top View)



 $\frac{XX}{\underline{Y}} : Identification Code \\ \underline{Y} : Year : 0~9$

- W : Week : A~Z : 1~26 week; a~z : 27~52 week; z represents
 - 52 and 53 week
- \underline{X} : Internal Code

Device	Package	Identification Code
AP7363ADJ	U-DFN2030-8	SA
AP7363-10	U-DFN2030-8	SB
AP7363-12	U-DFN2030-8	SC
AP7363-15	U-DFN2030-8	SD
AP7363-18	U-DFN2030-8	SE
AP7363-25	U-DFN2030-8	SF
AP7363-33	U-DFN2030-8	SG

(2) SO-8EP



(3) SOT223

(4) TO252





Package Outline Dimensions (All dimensions in mm.)

Please see http://www.diodes.com/package-outlines.html for the latest version.

1) U-DFN2030-8



	U-DFN2030-8					
Dim	Min	Max	Тур			
Α	0.57	0.63	0.60			
A1	0	0.05	0.02			
A3	-	-	0.15			
b	0.20	0.30	0.25			
D	1.95	2.05	2.00			
D2	1.40	1.60	1.50			
е	-	1	0.50			
Е	2.95	3.05	3.00			
E2	1.50	1.70	1.60			
L	0.35	0.45	0.40			
Z	-	-	0.125			
All	Dimen	sions	in mm			

2) SO-8EP



	SO-8EP						
Dim	Min	Max	Тур				
Α	1.40	1.50	1.45				
A1	0.00	0.13	-				
b	0.30	0.50	0.40				
С	0.15	0.25	0.20				
D	4.85	4.95	4.90				
Е	3.80	3.90	3.85				
E0	3.85	3.95	3.90				
E1	5.90	6.10	6.00				
e	-	1	1.27				
F	2.75	3.35	3.05				
Н	2.11	2.71	2.41				
Ĺ	0.62	0.82	0.72				
Ν	-	-	0.35				
Q	0.60	0.70	0.65				
All Di	mensi	ons in	mm				



Package Outline Dimensions (continued) (All dimensions in mm.)

Please see http://www.diodes.com/package-outlines.html for the latest version.

3) SOT223



SOT223							
Dim	Min	Max	Тур				
Α	1.55	1.65	1.60				
A1	0.010	0.15	0.05				
b	0.60	0.80	0.70				
b1	2.90	3.10	3.00				
С	0.20	0.30	0.25				
D	6.45	6.55	6.50				
Е	3.45	3.55	3.50				
E1	6.90	7.10	7.00				
е	-	-	4.60				
e1	-	-	2.30				
L	0.85	1.05	0.95				
Q	0.84	0.94	0.89				
All [Dimens	ions in	mm				

4) TO252 (Standard)



Option A (Top View) (Top View)



Option A (Bottom View)



Option B (Bottom View)

Т	TO252 (Standard)					
Dim	Min	Max	Тур			
Α	2.19	2.39	2.29			
A1	0.00	0.13	0.08			
A2	0.97	1.17	1.07			
b	0.64	0.88	0.783			
b2	0.76	1.14	0.95			
b3	5.21	5.46	5.33			
С	0.45	0.58	0.531			
D	6.00	6.20	6.10			
D1	5.21	-	-			
е	-	-	2.286			
Е	6.45	6.70	6.58			
E1	4.32	-	-			
Н	9.40	10.41	9.91			
L	1.40	1.78	1.59			
L3	0.88	1.27	1.08			
L4	0.60	1.02	0.83			
а	0°	10°	-			
All	Dimen	sions i	n mm			



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

1) U-DFN2030-8



Dimensions	Value
	(in min)
C	0.500
G	0.250
Х	0.350
X1	1.500
X2	1.850
Y	0.600
Y1	1.600
Y2	3.300

2) SO-8EP



Dimensions	Value (in mm)
С	1.270
Х	0.802
X1	3.502
X2	4.612
Y	1.505
Y1	2.613
Y2	6.500



Suggested Pad Layout (continued)

Please see http://www.diodes.com/package-outlines.html for the latest version.

3) SOT223



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

4) TO252 (Standard)



Dimensions	Value (in mm)
С	4.572
Х	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

Mechanical Data

- Moisture Sensitivity: Level 1 Per J-STD-020
- Terminals:
 - SOT223/ SO-8EP/ TO252 : Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 3
 - U-DFN2030-8: Finish NiPdAu over Copper Leads, Solderable per MIL-STD-202, Method 208 (4)
- Weight:
 - U-DFN2030-8: 0.0105 grams (Approximate)
 - SOT223: 0.113 grams (Approximate)
 - SO-8EP: 0.081 grams (Approximate)
 - TO252: 0.315 grams (Approximate)



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